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(54) **PRODUCTION OF RESIN MOLD FOR MOLDING**

(57) Abstract:

PURPOSE: To improve the adhesion of a metallic film to the body of a resin mold by coating the body with a coating material contg. Pd and Cu dispersed in bisphenol A type epoxy resin before the formation of the film on the body electroless plating.

CONSTITUTION: When the least the split surfaces of the body of a resin mold and the surface of the cavity of a product are covered with metallic films, the body is first degreased by washing with methanol or the like.

The degreased body is coated with a coating material contg. Pd and Cu dispersed in bisphenol A type epoxy resin by spraying or other method, and a formed film is dried at about 150W200°C for about 20W40min and activated by acid treatment and washing. Metallic films are then formed on the catalyzed body of the resin mold with an electroless plating bath such as an Ni-P bath. The metallic films can be formed with satisfactory adhesion and the covered resin mold can be used over a long period.

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